



Material Content Data Sheet



Sales Product Name				IPD60R520C6		Issued		23. January 2015	
MA#				MA001318920					
Package				PG-TO252-3-313		Weight*		318.96 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.425	1.07	1.07	10739	10739	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		462		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	copper	7440-50-8	147.096	46.13	46.19	461172	461773	
wire	non noble metal	aluminium	7429-90-5	0.489	0.15	0.15	1533	1533	
encapsulation	organic material	carbon black	1333-86-4	1.403	0.44		4400		
	plastics	epoxy resin	-	24.560	7.70		77001		
	inorganic material	silicondioxide	60676-86-0	114.381	35.86	44.00	358606	440007	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11726	11726	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4454	4465	
solder	noble metal	silver	7440-22-4	0.076	0.02		239		
	non noble metal	tin	7440-31-5	0.061	0.02		191		
	non noble metal	lead	7439-92-1	2.910	0.91	0.95	9124	9554	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60125	60203	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com